

Data Sheet

July 1999

File Number

1691.3

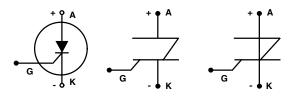
### Gate Controlled Unidirectional Transient Surge Suppressors (TO-202 Surgector)

Surgector transient surge protectors are designed to protect telecommunication equipment, data links, alarm systems, power supplies, and other sensitive electrical circuits from damage that could be caused by switching transients, lightning strikes, load changes, commutation spikes, and line crosses.

These devices are fast turn-on, high holding current thyristors. When coupled with a user supplied voltage level detector, they provide excellent voltage limiting even on very fast rise time transients. The high holding current allows this surgector to return to its high impedance off state after a transient.

The surgector device's normal off-state condition in the forward blocking mode is a high impedance, low leakage state that prevents loading of the line.

#### Equivalent Schematic Symbols



#### **Features**

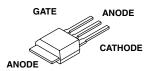
- Blocking Voltage 100V and 270V
- · Peak Transient Surge Current
- · High Minimum Holding Current, 100mA or 270mA
- · Low On-State Voltage
- UL Recognized File # E135010 to STD 497B

#### **Applications**

- · Telecommunications Equipment
- · Data and Voice Lines
- Modems
- · Alarm Systems

### **Packaging**

**MODIFIED TO-202** 



# SGT27S10, SGT27S23

## **Absolute Maximum Ratings** $T_C = 25^{\circ}C$

	SGT27S10 SGT27S23	UNITS
Continuous Off State Voltage:		
V <sub>DM</sub>	270	V
V <sub>RM</sub>	1	V
Transient Peak Surge Current: I <sub>TSM</sub>		
1µs x 2µs (Note 1)	300	Α
8µs x 20µs	200	Α
10µs x 560µs	125	Α
10µs x 1000µs	100	Α
One Half Cycle, 1 every 30s	60	Α
One Second, Halfwave	30	Α
Operating Temperature (T <sub>A</sub> )	-40 to 85	°C
Storage Temperature Range (T <sub>STG</sub> )	-40 to 150	°C
NOTE:		

<sup>1.</sup> Unit designed not to fail open below 450A.

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

### **Electrical Specifications** At Case Temperature, $T_C = 25^{\circ}C$ , Unless Otherwise Specified

PARAMETER	TEST CONDITIONS	TEST	SGT27S23			SGT27S10			
		_	MIN	TYP	MAX	MIN	TYP	МАХ	UNITS
Off-State Current	I <sub>DM</sub>	$V_{DM} = 270V$ $T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$	- -	- -	- -	- -	- -	100 50	nA μA
Off-State Current	I <sub>RM</sub>	$V_{RM} = 1V$ $T_A = 25^{\circ}C$ $T_A = 85^{\circ}C$	- -		1 10	- -		1 10	mA mA
Breakover Voltage	V <sub>BO</sub>	dv/dt = 100V/μs (Note 2)	-	-	285	-	-	285	V
Holding Current	I <sub>H</sub>		230	-	-	100	-	-	mA
On-State Voltage	V <sub>T</sub>	I <sub>T</sub> = 10A	-	-	2	-	-	2	V
Gate-Trigger Current	I <sub>GT</sub>		-	-	175	-	-	150	mA
Main Terminal Capacitance	co	V <sub>DM</sub> = 0V V <sub>DM</sub> = 50V at 1MHz		90 50	-	-	90 50	-	pF pF

#### NOTE:

2. External Zener diode from anode to gate: 270V (SGT27S10).

#### Performance Curves

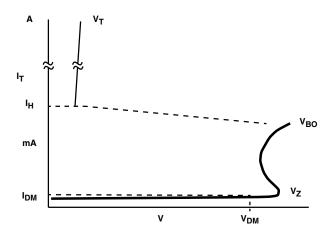


FIGURE 1. TYPICAL VOLT-AMPERE CHARACTERISTICS

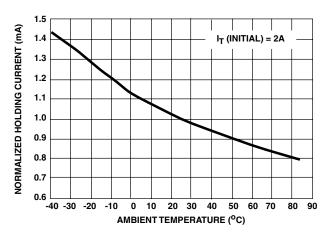
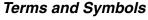


FIGURE 3. NORMALIZED HOLDING CURRENT vs
TEMPERATURE



**V<sub>DM</sub>** (Maximum Off-State Voltage) - Maximum off-state voltage (DC or peak) which may be applied continuously.

 ${
m V_{RM}}$  (Maximum Reverse Voltage) - Maximum reverse-blocking voltage (DC or peak) which may be applied.

**I<sub>TSM</sub> (Maximum Peak Surge Current) -** Maximum nonrepetitive current which may be allowed to flow for the time state.

 $\textbf{T}_{\pmb{\mathsf{A}}} \text{ (Ambient Operating Temperature) - } \textbf{Ambient} \\ \text{temperature range permitted during operation in a circuit.}$ 

**T<sub>STG</sub>** (Storage Temperature) - Temperature range permitted during storage.

 $I_{DM}$  (Off-State Current) - Maximum value of off-state current that results from the application of the maximum off-state voltage ( $V_{DM}$ ).

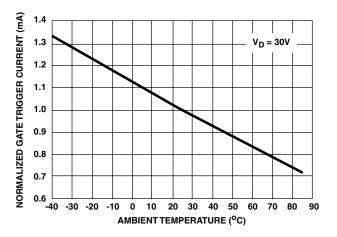


FIGURE 2. NORMALIZED GATE-TRIGGER CURRENT vs TEMPERATURE

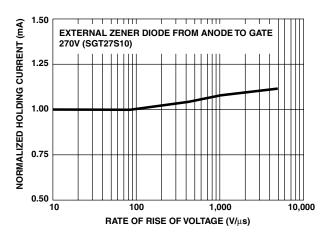


FIGURE 4. NORMALIZED V<sub>BO</sub> vs dv/dt

**I<sub>RM</sub> (Reverse Current) -** Maximum value of reverse current that results from the application of the maximum reverse voltage (V<sub>RM</sub>).

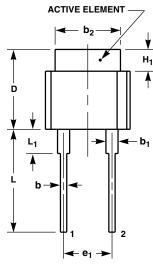
I<sub>H</sub> (Holding Current) - Minimum on-state current that will hold the device in the on-state after it has been latched on.

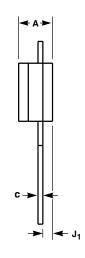
V<sub>T</sub> (On-State Voltage) - Voltage across the main terminals for a specified on-state current.

I<sub>GT</sub> (Gate-Trigger Current) - Minimum gate current which will cause the device to switch from the off-state to the on-state.

**C**<sub>O</sub> (Main Terminal Capacitance) - Capacitance between the main terminals at a specified off-state voltage.

### **Mechanical Dimensions**







### **TO-202 Modified**

### 2 LEAD JEDEC STYLE TO-202 SHORT TAB PLASTIC PACKAGE

	INCHES		MILLIM		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
Α	0.130	0.150	3.31	3.81	-
b	0.024	0.028	0.61	0.71	2, 3
b <sub>1</sub>	0.045	0.055	1.15	1.39	1, 2, 3
b <sub>2</sub>	0.270	0.280	6.86	7.11	-
С	0.018	0.022	0.46	0.55	1, 2, 3
D	0.320	0.340	8.13	8.63	-
Е	0.340	0.360	8.64	9.14	-
e <sub>1</sub>	0.200 BSC		5.08 BSC		4
H <sub>1</sub>	0.080	0.100	2.04	2.54	-
J <sub>1</sub>	0.039	0.049	1.00	1.24	5
L	0.410	0.440	10.42	11.17	-
L <sub>1</sub>	0.080	0.100	2.04	2.54	1

#### NOTES:

- 1. Lead dimension and finish uncontrolled in L<sub>1</sub>.
- 2. Lead dimension (without solder).
- 3. Add typically 0.002 inches (0.05mm) for solder coating.
- 4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D
- 5. Position of lead to be measured 0.100 inches (2.54mm) from bottom of dimension D.
- 6. Controlling dimension: Inch.
- 7. Revision 3 dated 10-94.

## **Ordering Information**

